CLAIMS

1. A resin sheet for sealing an electronic device comprising a filler, ~~wherein~~

wherein a water absorption rate is 0.3% by weight or less after the resin sheet is left under an atmosphere of 85°C and 85%RH for 168 hours, ~~and~~

wherein the filler is dispersed substantially in a state of primary particles, ~~.~~

wherein there is substantially no aggregate with a size of 300 μm or more in the resin sheet,

~~2. The resin sheet for sealing an electronic device according to claim 1,~~ wherein the filler is treated with a silane coupling agent, and

wherein the silane coupling agent has at least one member selected from the group consisting of a vinyl group, an epoxy group, a styryl group, a methacrylic group, an acrylic group, a mercapto group, a sulfide group, and an isocyanate group.

2~~3~~. The resin sheet for sealing an electronic device according to claim 1 ~~or 2~~, wherein a content of the filler in the resin sheet for sealing an electronic device is 70 to 90% by volume.

3~~4~~. A method of manufacturing an electronic device package, the method comprising:

a laminating step of laminating the resin sheet for sealing an electronic device according to ~~any of~~ claim~~s~~ 1

or 2~~to 3~~ on one or a plurality of electronic devices so as to cover the electronic devices; and

a sealing body forming step of curing the resin sheet for sealing an electronic device to form a sealing body.